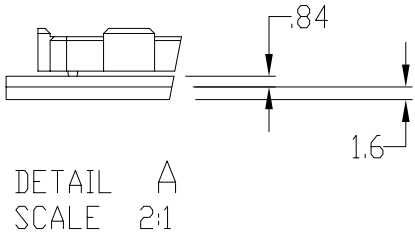
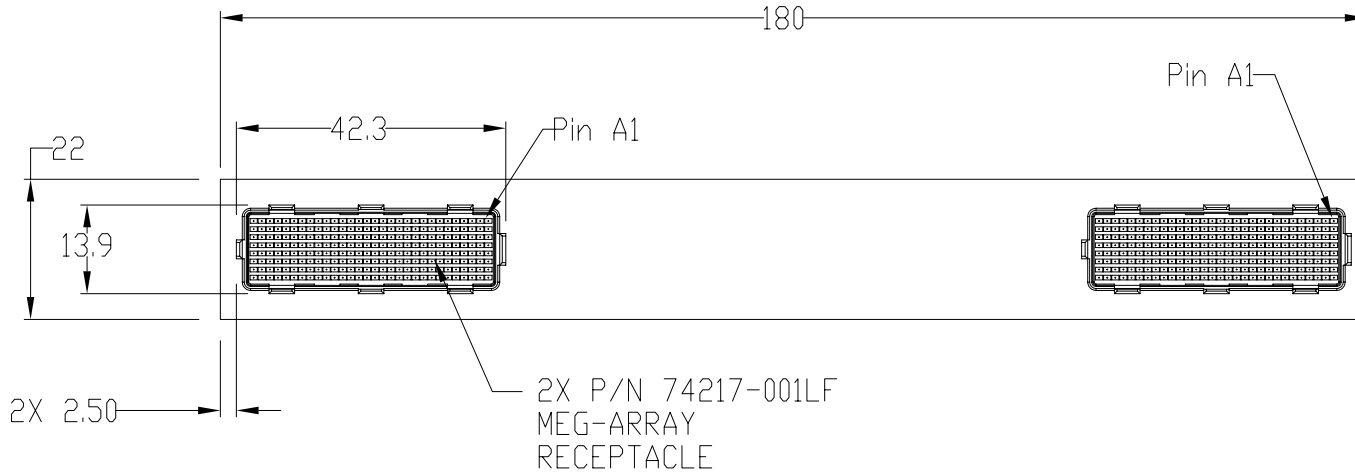


PRODUCT NUMBER
10061262-001LF



mat'l. code SEE NOTES				surface ASME Y14.5	tolerance ASME Y14.5	projection ASME Y14.5	product family
ltr	ecn no	dr	date	tolerances unless otherwise specified		MM	title
A	V06-0065	DAI	01/25/06	angle	.X ±.3	FCI	FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES
B	V06-0112	DAI	02/06/06	0° ±2'	.XX ±.10		
C	V07-0276	DAI	2007-04-05		.XXX ±.050		
				dr	D.INGRAM	01/25/06	dwg no
				eng	D.BRANN	01/25/06	sheet 1 of 2
				chr	D.BRANN	01/25/06	size
				appd	D.BRANN	01/25/06	A4
sheet index	revision sheet	c	c				type
	1	2					CUSTOMER Drawing

PRODUCT NUMBER
10061262-001LF

NOTES:

1. MATERIAL:

- HOUSING: LCP
- CONTACT: COPPER ALLOY
- CONTACT PLATING: 38µm (15µ in) Au OVER Ni
- SOLDER BALL PLATING: SnAgCu
- BACKER BOARD: G-10
- FLEX CIRCUIT: Polyimide

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHEMENT.

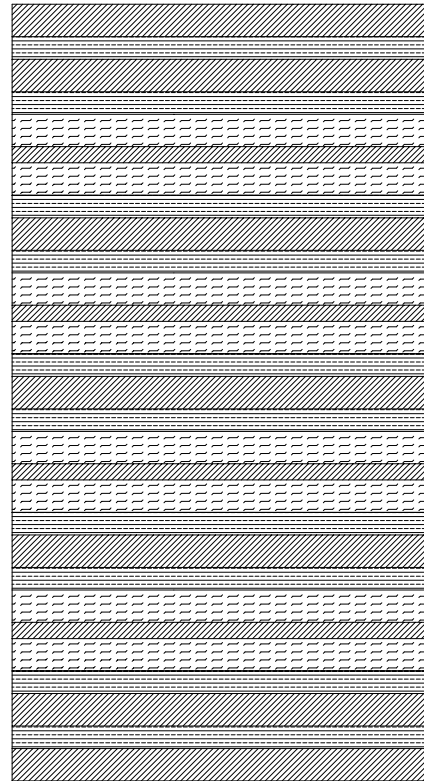
3. LEAD FREE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

4. FOR PROPER APPLICATION, FOLLOW FCI APPLICATION SPECIFICATION GS-20-033.

5. CONSTRUCTION PER IPC-6013 CLASS II TYPE 3 OR 4.

6. MEG-ARRAY PRODUCT SPECIFICATION: GS-12-100.

Cover coat
1/2 OZ Copper
Adhesive
Polyimide



.81/.84

A

A

B

B

mat'l. code SEE NOTES		surface ASME Y14.5	tolerance ASME Y14.5	projection 	product family
ltr	ecn no dr	date	tolerances unless otherwise specified		title
c			angle 0° ±2'	MM	FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES
			.X ±.3	scale 1:1	dwg no
			.XX ±.10		sheet 2 of
			.XXX ±.050		size
		dr	D.INGRAM	01/25/06	10061262
		eng	D.BRANN	01/25/06	A4
		chr	D.BRANN	01/25/06	type
		appd	D.BRANN	01/25/06	CUSTOMER Drawing
sheet index	revision sheet				